



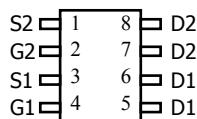
**ALPHA & OMEGA**  
SEMICONDUCTOR, LTD



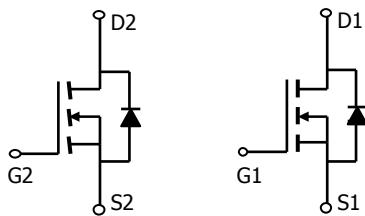
**AO4840**

## Dual N-Channel Enhancement Mode Field Effect Transistor

General Description	Features
<p>The AO4840 uses advanced trench technology MOSFETs to provide excellent <math>R_{DS(ON)}</math> and low gate charge. This dual device is suitable for use as a load switch or in PWM applications. <i>Standard Product AO4840 is Pb-free (meets ROHS &amp; Sony 259 specifications). AO4840L is a Green Product ordering option. AO4840 and AO4840L are electrically identical.</i></p>	<p><math>V_{DS}</math> (V) = 40V  <math>I_D</math> = 6A (<math>V_{GS}</math>=10V)  <math>R_{DS(ON)} &lt; 31m\Omega</math> (<math>V_{GS}</math>=10V)  <math>R_{DS(ON)} &lt; 45m\Omega</math> (<math>V_{GS}</math>=4.5V)</p>



SOIC-8



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Max	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>A</sup>	$I_D$	6	A
$T_A=70^\circ\text{C}$		5	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	20	
Power Dissipation	$P_D$	2	W
$T_A=70^\circ\text{C}$		1.28	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{0JA}$	48	62.5	°C/W
Maximum Junction-to-Ambient <sup>A</sup>		74	110	°C/W
Maximum Junction-to-Lead <sup>C</sup>	$R_{0JL}$	35	50	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=10\text{mA}, V_{GS}=0\text{V}$	40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=32\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1	$\mu\text{A}$
					5	
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	2.3	3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	20			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=6\text{A}$ $T_J=125^\circ\text{C}$		25	31	$\text{m}\Omega$
				36	48	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=6\text{A}$		22		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.75	1	V
$I_S$	Maximum Body-Diode Continuous Current				3	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=20\text{V}, f=1\text{MHz}$		404		pF
$C_{\text{oss}}$	Output Capacitance			95		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			37		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		2.7		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, I_D=6\text{A}$		8.3		nC
$Q_g(4.5\text{V})$	Total Gate Charge			4.2		nC
$Q_{\text{gs}}$	Gate Source Charge			1.3		nC
$Q_{\text{gd}}$	Gate Drain Charge			2.3		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, R_L=3.3\Omega, R_{\text{GEN}}=3\Omega$		4.2		ns
$t_r$	Turn-On Rise Time			3.3		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			15.6		ns
$t_f$	Turn-Off Fall Time			3		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		20.5		ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		14.5		nC

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\text{JL}}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 $\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

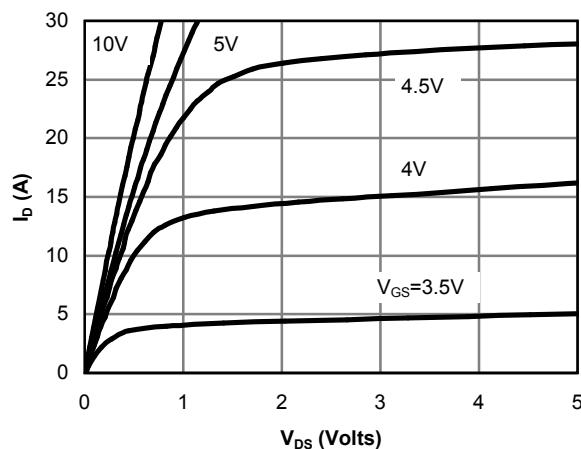


Fig 1: On-Region Characteristics

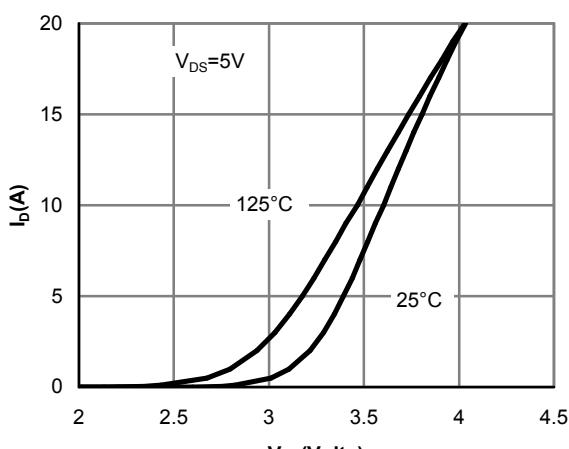


Figure 2: Transfer Characteristics

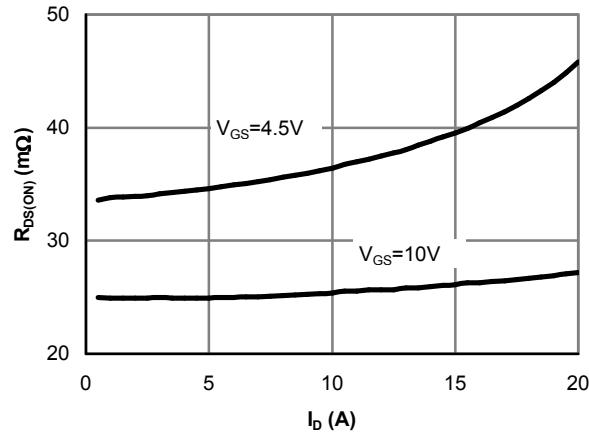


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

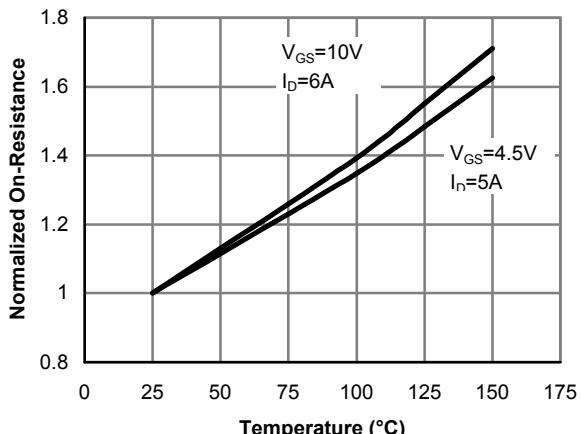


Figure 4: On-Resistance vs. Junction Temperature

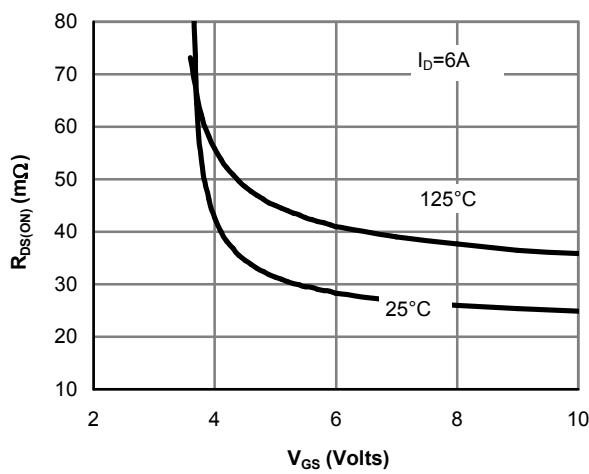


Figure 5: On-Resistance vs. Gate-Source Voltage

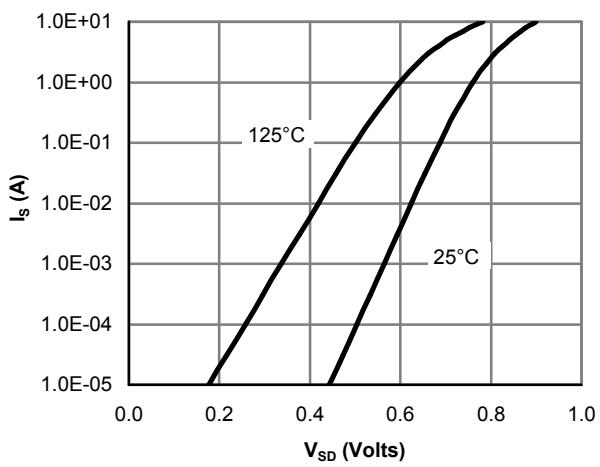


Figure 6: Body-Diode Characteristics

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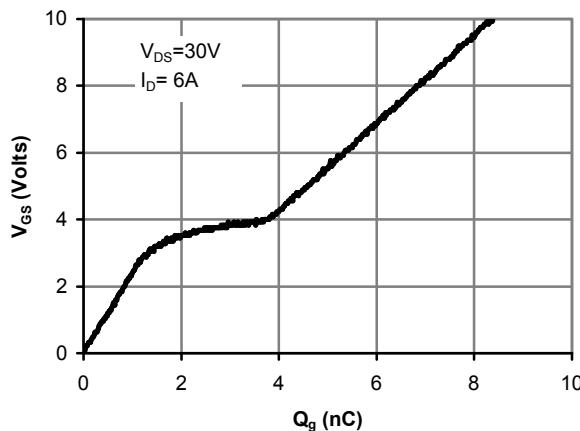


Figure 7: Gate-Charge Characteristics

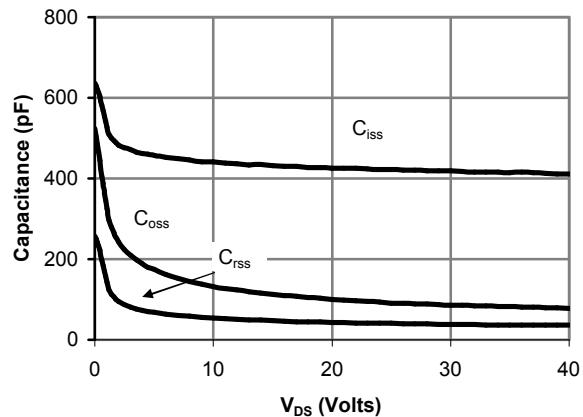


Figure 8: Capacitance Characteristics

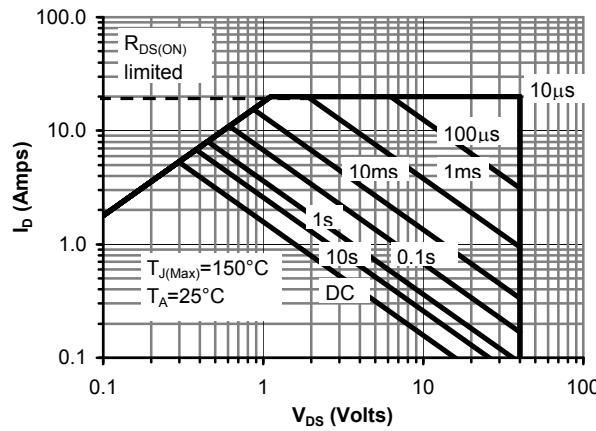


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

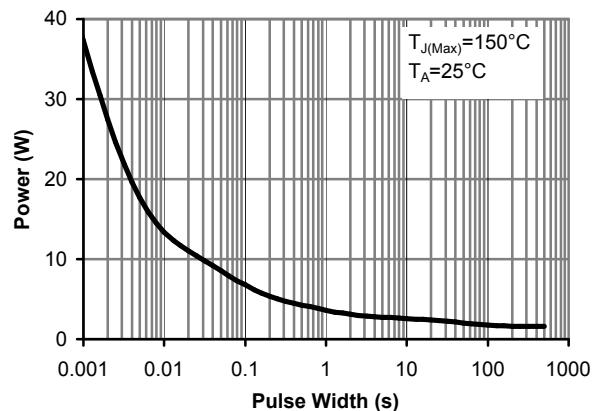


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

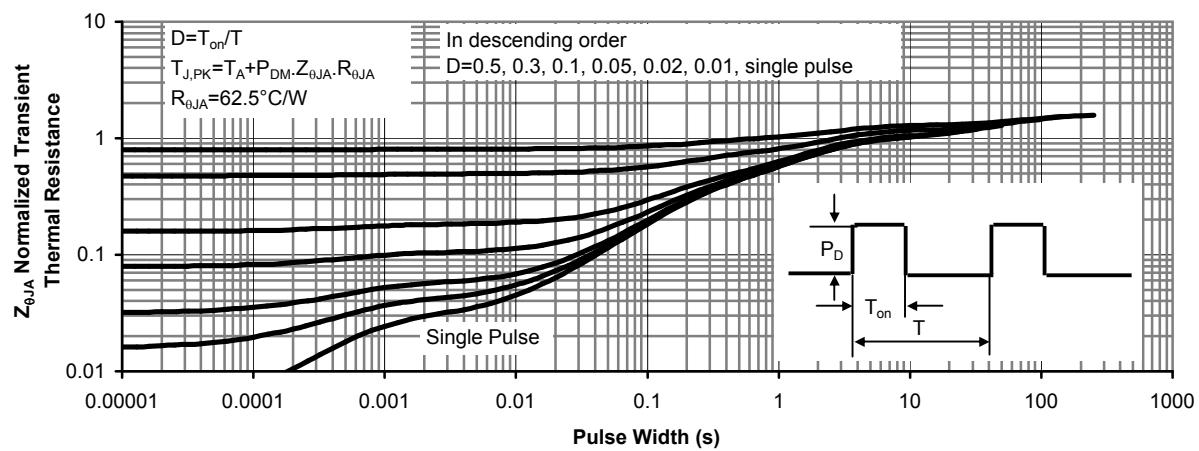


Figure 11: Normalized Maximum Transient Thermal Impedance